

RoHS

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

SPECIFICATIONS
Rated Current:1.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:500V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:-40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V-0)
Standard: PA6T
Max.Processing Temp: 230°C for 30-60 seconds
(260°C for 10 seconds)

Ordering Information
HC-BH732 XX R XX X B K00 X 01

No.of Pins 10-100P
Contact G0:Gold Flash
G1:3U" Gold
G2:5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
S0:Gold Flash/Tin
SN:Tin
Plating Option
A=BK-PBT
B=BK-PA66
C=BK-PA6T
D=BK-PA46
E=BK-PA9T
F=BK-LCP
Insulator Material
Option
A=BK-PBT
B=BK-PA66
C=BK-PA6T
D=BK-PA46
E=BK-PA9T
F=BK-LCP
Packing
O=PE Bag
A=Tray
T=Tube
P=Tube+Cap
R=Reel+Cap

				OPERATION		DRAW	Ayang	SCALE		FIT	HECON 东莞市禾康电子有限公司 DONGGUAN HECON ELECTRONICS CO.,LTD	
				X.X	±0.30	CHECK		UNIT	mm	PART NO.	HC -BH732XXRXBXBK00X01	
				X.XX	±0.20			SIZE	A4			
				X.XXX	±0.10			SHEET	1/1			
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	±3'	APPROVE		PROJ.	◆	TITLE:	1.27mm H5.7 Right Angle Npin L=10.0/12.5 Box Header	
1				DIM	TOL	5						

Max. Processing Temp: 230°C for 30–60 seconds
(260°C for 10 seconds)

HC-BH732 XX R XX X B K00 X 01

Packing
0=PE Bag
A=Tray
T=Tube
P=Tube+Cap
R=Reel+Cap

				OPERATION		DRAW	Ayang		SCALE	FIT	HECON 东莞市禾康电子有限公司 DONGGUAN HECON ELECTRONICS CO.,LTD	
				X.X	±0.30					UNIT		
				X.XX	±0.20	CHECK			SIZE	A4	PART NO.	HC-BH732XXRXXXBK00X01
				X.XXX	±0.10				SHEET	1/1		
A0		NEW DRAWING		Angle	±3°	APPROVE			SHEET	1/1	TITLE:	1.27mm H5.7 Right Angle Npin L=10.0/12.5 Box Header
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL				PROJ.			